

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HIDEJI TAJIMA	02/21/2019
TAKAKI SUGIMOTO	02/16/2019
TETSUYA UEDA	02/02/2019
RECEIVING PARTY DATA	
Name:	UNIVERSAL BIO RESEARCH CO., LTD.
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Internal Address:	MATSUDO-SHI
City:	CHIBA
State/Country:	JAPAN
Postal Code:	271-0064
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16060556
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ATTORNEY DOCKET NUMBER:	10287.174US01
NAME OF SUBMITTER:	ALAN N. HERDA
SIGNATURE:	/ALAN N. HERDA/
DATE SIGNED:	02/26/2019
Total Attachments: 2	
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source=10287-174US01-Assignment#page2.tif	

ASSIGNMENT

WHEREAS, We, **Hideji TAJIMA, Takaki SUGIMOTO, and Tetsuya UEDA, of Matsudo-shi, Chiba, Japan**, have invented designs and certain improvements in:

ABSORBANCE MEASURING DEVICE AND METHOD THEREOF

for which an application for Letters Patent of the United States of America has been filed and accorded U.S. Application No. 16/060,556.


WHEREAS, **UNIVERSAL BIO RESEARCH CO., LTD.** (Assignee), a Japanese corporation, having its principal office and place of business at 88 Kamihongou, Matsudo-shi, Chiba 271-0064 Japan, is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said Assignee, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said application, and all divisionals, renewals, substitutionals and continuing applications thereof, and all Letters Patents of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patents which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner for Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

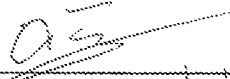
AND We HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND We HEREBY further covenant and agree that we will communicate to said Assignee, its successors, legal representatives and assigns, any facts known to us respecting said inventions, and testify in any legal proceedings, sign all lawful papers, execute all divisionals, renewals, substitutionals, continuing applications and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said Assignee, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said inventions in all countries.

[SIGNATURE PAGE FOLLOWS]

Inventor: 
Hideji TAJIMA

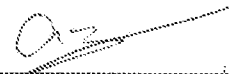
Date: Feb 21, 2019

Witness: 
Name: Atsuhiko Takahashi

Date: 2019.02.21

Inventor: 
Takaki SUGIMOTO


Date: Feb 16, 2019

Witness: 
Name: Atsuhiko Takahashi

Date: 2019.02.21

Inventor: 
Tetsuya UEDA

Date: Feb 2, 2019

Witness: 
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Date: 2019.02.21